

- Call for Papers -



7th SEATUC Symposium

Venue: Institut Teknologi Bandung, INDONESIA
March 4 - 6 2013

South East Asian Technical University Consortium (SEATUC) will organize its 7th international symposium. The symposium provides an opportunity for prominent researchers, engineers and practitioners who serves as faculty members of SEATUC member universities* to present the latest research in any of the following 11 fields.

- OS01:** Energy, Environment, and Earth System Science
- OS02:** Information and Communication Technology
- OS03:** Architecture, Urban Planning and Design
- OS04:** Bioscience, Biological, and Engineering Science
- OS05:** Robotics and Mechanical Engineering
- OS06:** Materials Science and Engineering
- OS07:** Basic Science
- OS08:** Transportation Engineering
- OS09:** Applied Mathematics and Informatics
- OS10:** Electrical Engineering
- OS11:** Electronics and Telecommunications

*consortium member universities

Hanoi University of Science and Technology
Ho Chi Minh City University of Technology
Institut Teknologi Bandung
King Mongkut's University of Technology Thonburi
Shibaura Institute of Technology
Suranaree University of Technology
Universitas Gadjah Mada
University of Technology Malaysia

Paper Submission

The paper submission has to be made through the international office of the university where the applicants belong. Four pages are allowed for each paper and should be submitted electronically in MS Word file format.

Paper Publication

The submitted original papers are formed into proceedings. Therefore, please consider about the paper's copyright as the submitted papers are to be transferred to SEATUC Symposium Organizing Committee and subject to be officially published by acquiring ISBN (International Standard Book Number)

Important Date

1. Abstract Submission - 30th October 2012
2. Deadline for submission of full papers - 30th November 2012
3. Notification of acceptance - 15th January 2013
4. Deadline registration - 20th January 2013

Organized by:



Paper Submission and Contacts :
International Office of applicant's home institute